

More flexible than ever before: Kienle + Spiess bonding technology glulock®

Kienle + Spiess now offers three versions of this tried-and-tested bonding technology that cater to different requirements and applications.

With **glulock®**, customers receive the proven original. **glulock HT** can also be used at high temperatures, while **glulock MD** enables the user to choose the number of bonding points.

Kienle + Spiess sets new standards: **glulock Multiple Dots** makes a further step towards increasing the bonding strength of the package assembly of loose rotor and stator laminations. In addition to the possible applications on the yoke, **glulock MD** technology can also be used to apply adhesive to the bridge.

Thanks to an optimised control system, the glue is applied more precisely and consistently, so bonding is almost completely flat and the available surface can be used efficiently.

Patentnummer: glulock 1 EP 1833145, gulock 2 (HT) EP 2 826 136